

DSG-RICH R&D Meeting

Date: August 3, 2021

Time: 9:30 AM – 10:00 AM

Attendees: Mary Ann Antonioli, Peter Bonneau, Aaron Brown, Pablo Campero, Brian Eng, George Jacobs, Mindy Leffel, Tyler Lemon, Marc McMullen, and Amrit Yegneswaran

1. SHT35 sensor PCBs' production order to be placed

Peter Bonneau, Aaron Brown, Pablo Campero, Brian Eng, Tyler Lemon, and Marc McMullen

1. Production order of 50 PCBs will be placed for 3-week fabrication time and 7-day assembly time

2. Procurement of hardware interlock system's chassis components

Tyler Lemon

1. Procurement of chassis hardware will start to ensure all parts are procured before August 30, FY2021 deadline

3. Organizing order sensors are read on backplane PCB

Peter Bonneau, Tyler Lemon, and Marc McMullen

1. Twelve N₂ volume sensors will be on top row of RJ45 ports and twelve electronic panel sensors on bottom row
2. Organizing will be done by re-mapping DIO channels so the sensors are read by order of backplane port rather than DIO channel